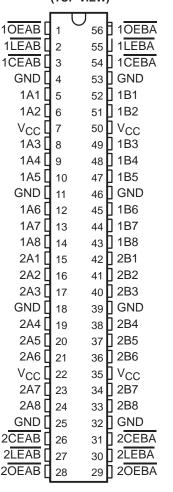
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- **Members of the Texas Instruments** Widebus™ Family
- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low Static-Power Dissipation
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V<sub>CC</sub>)
- **Support Unregulated Battery Operation** Down to 2.7 V
- I<sub>off</sub> and Power-Up 3-State Support Hot Insertion
- Bus Hold on Data Inputs Eliminates the **Need for External Pullup/Pulldown** Resistors
- Typical V<sub>OLP</sub> (Output Ground Bounce)  $< 0.8 \text{ V at V}_{CC} = 3.3 \text{ V}, T_A = 25^{\circ}\text{C}$
- Distributed V<sub>CC</sub> and GND Pin Configuration **Minimizes High-Speed Switching Noise**
- Flow-Through Architecture Optimizes PCB Layout
- Latch-Up Performance Exceeds 500 mA Per **JESD 17**
- **ESD Protection Exceeds 2000 V Per** MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- **Package Options Include Plastic Shrink** Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package **Using 25-mil Center-to-Center Spacings**

#### SN54LVTH16543 . . . WD PACKAGE SN74LVTH16543... DGG OR DL PACKAGE (TOP VIEW)



#### description

The 'LVTH16543 devices are 16-bit registered transceivers designed for low-voltage (3.3-V) V<sub>CC</sub> operation, but with the capability to provide a TTL interface to a 5-V system environment. These devices can be used as two 8-bit transceivers or one 16-bit transceiver. Separate latch-enable (LEAB or LEBA) and output-enable (OEAB or OEBA) inputs are provided for each register to permit independent control in either direction of data flow.

The A-to-B enable (CEAB) input must be low to enter data from A or to output data from B. If CEAB is low and LEAB is low, the A-to-B latches are transparent; a subsequent low-to-high transition of LEAB puts the A latches in the storage mode. With CEAB and OEAB both low, the 3-state B outputs are active and reflect the data present at the output of the A latches. Data flow from B to A is similar but requires using the  $\overline{\sf CEBA}$ ,  $\overline{\sf LEBA}$ , and  $\overline{\sf OEBA}$ inputs.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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## description (continued)

When  $V_{CC}$  is between 0 and 1.5 V, the devices are in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

These devices are fully specified for hot-insertion applications using  $I_{off}$  and power-up 3-state. The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

The SN54LVTH16543 is characterized for operation over the full military temperature range of  $-55^{\circ}$ C to  $125^{\circ}$ C. The SN74LVTH16543 is characterized for operation from  $-40^{\circ}$ C to  $85^{\circ}$ C.

FUNCTION TABLE† (each 8-bit section)

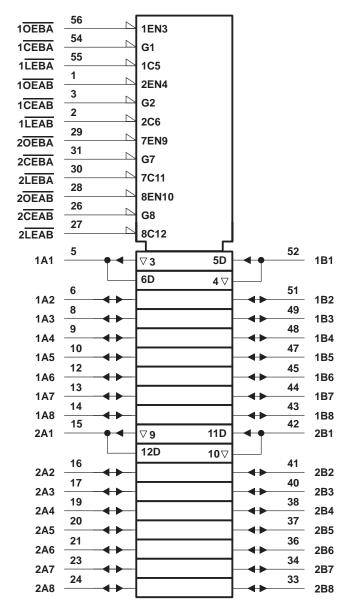
	•		-								
	INPUTS										
CEAB	LEAB	OEAB	Α	В							
Н	Х	Х	Х	Z							
Х	Χ	Н	Χ	Z							
L	Н	L	Χ	в <sub>0</sub> ‡							
L	L	L	L	L							
L	L	L	Н	Н							

TA-to-B data flow is shown; B-to-A flow control is the same except that it uses CEBA, LEBA, and OEBA.



<sup>&</sup>lt;sup>‡</sup>Output level before the indicated steady-state input conditions were established

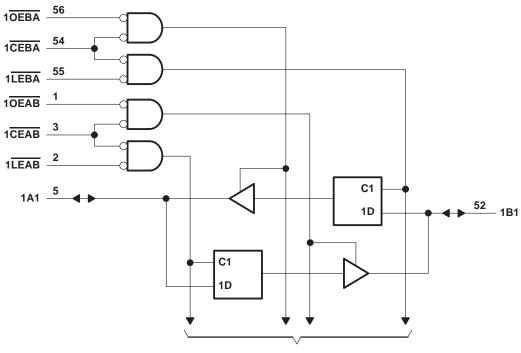
## logic symbol†



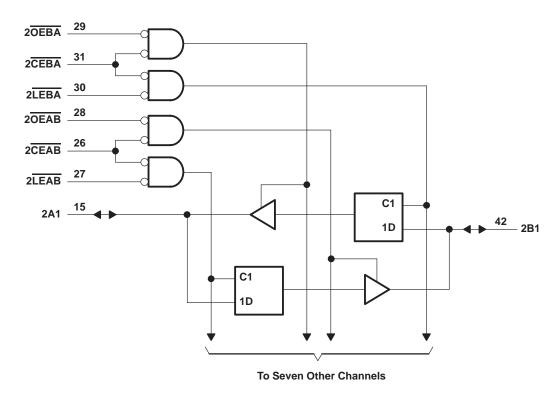
<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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## logic diagram (positive logic)



To Seven Other Channels





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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	–0.5 V to 4.6 V
Input voltage range, V <sub>I</sub> (see Note 1)	
Voltage range applied to any output in the high-impedance	
or power-off state, V <sub>O</sub> (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high state, V <sub>O</sub> (see Note 1)0.5 V	to $V_{CC}$ + 0.5 $V$
Current into any output in the low state, IO: SN54LVTH16543	96 mA
SN74LVTH16543	128 mA
Current into any output in the high state, IO (see Note 2): SN54LVTH16543	48 mA
SN74LVTH16543	64 mA
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–50 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	–50 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 3): DGG package	81°C/W
DL package	74°C/W
Storage temperature range, T <sub>stq</sub>	-65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
  - 2. This current flows only when the output is in the high state and  $V_O > V_{CC}$ .
  - 3. The package thermal impedance is calculated in accordance with JESD 51.

## recommended operating conditions (see Note 4)

			SN54LVTI	116543	SN74LVTI	116543	UNIT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		2.7	3.6	2.7	3.6	V
VIH	High-level input voltage		2	2	2		V
V <sub>IL</sub>	Low-level input voltage			0.8		0.8	V
VI	Input voltage		4	5.5		5.5	V
ЮН	High-level output current		1	-24		-32	mA
loL	Low-level output current		2	48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	20/	10		10	ns/V
Δt/ΔV <sub>CC</sub>	Power-up ramp rate		200		200		μs/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 4: All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

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## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DAD	AMETER	TEST C	ONDITIONS	SN5	4LVTH16	6543	SN7	4LVTH16	6543	UNIT
PAR	RAMETER	1531 CC	ONDITIONS	MIN	TYP†	MAX	MIN	TYP†	MAX	UNII
VIK		$V_{CC} = 2.7 \text{ V},$	$I_I = -18 \text{ mA}$			-1.2			-1.2	V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V},$	I <sub>OH</sub> = -100 μA	V <sub>CC</sub> -0	.2		V <sub>CC</sub> -0	.2		
\/a++		$V_{CC} = 2.7 \text{ V},$	I <sub>OH</sub> = -8 mA	2.4			2.4			V
VOH		V <sub>CC</sub> = 3 V	I <sub>OH</sub> = -24 mA	2						V
		∧CC = 2 ∧	I <sub>OH</sub> = -32 mA				2			
	V <sub>CC</sub> = 2.7 V		I <sub>OL</sub> = 100 μA			0.2			0.2	
		VCC = 2.7 V	I <sub>OL</sub> = 24 mA			0.5			0.5	
VOL			I <sub>OL</sub> = 16 mA			0.4			0.4	V
VOL		V <sub>CC</sub> = 3 V	$I_{OL} = 32 \text{ mA}$			0.5			0.5	V
		VCC = 3 V	$I_{OL} = 48 \text{ mA}$			0.55				
	_		$I_{OL} = 64 \text{ mA}$						0.55	
	Control inputs	$V_{CC} = 3.6 \text{ V},$	$V_I = V_{CC}$ or GND			±1			±1	
	Control inputs	$V_{CC} = 0 \text{ or } 3.6 \text{ V},$	V <sub>I</sub> = 5.5 V		Ä	10				
l <sub>l</sub>			V <sub>I</sub> = 5.5 V	20			20			μΑ
	A or B ports‡	V <sub>CC</sub> = 3.6 V	AI = ACC							
			V <sub>I</sub> = 0				-5			
I <sub>off</sub>		$V_{CC} = 0$ ,	$V_I$ or $V_O = 0$ to 4.5 $V$	0	Ó,				±100	μΑ
		V <sub>CC</sub> = 3 V	V <sub>I</sub> = 0.8 V	75			75			
II(hold)	A or B ports	VCC = 3 V	V <sub>I</sub> = 2 V	-75			<b>-</b> 75			μΑ
		$V_{CC} = 3.6 \text{ V}$ ,	V <sub>I</sub> = 0 to 3.6 V						±500	
IOZPU		$\frac{V_{CC}}{OE}$ = 0 to 1.5 V, $V_{O}$ = $\frac{V_{CC}}{OE}$ = don't care	0.5 V to 3 V,			±100*			±100	μΑ
I <sub>OZPD</sub>		$\frac{\text{V}_{\text{C}}\text{C}}{\text{OE}} = 1.5 \text{ V to 0, V}_{\text{O}} = 0.5 \text{ O}$	0.5 V to 3 V,			±100*			±100	μА
		V <sub>CC</sub> = 3.6 V,	Outputs high			0.19			0.19	
ICC	$I_{O} = 0$ ,		Outputs low			5			5	mA
	$V_I = V_{CC}$ or GND		Outputs disabled			0.19			0.19	
ΔICC¶		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$ , One input at $V_{CC} - 0.6 \text{ V}$ , Other inputs at $V_{CC}$ or GND				0.2			0.2	mA
Ci				4			4		pF	
C <sub>io</sub>		V <sub>O</sub> = 3 V or 0			10			10		pF

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter is not production tested.



<sup>†</sup> All typical values are at  $V_{CC}$  = 3.3 V,  $T_A$  = 25°C. ‡ Unused pins at  $V_{CC}$  or GND

<sup>§</sup> This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

<sup>¶</sup> This is the increase in supply current for each input that is at the specified TTL voltage level rather than V<sub>CC</sub> or GND.

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# timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

				S	N54LV	ГН16543		S	N74LV	TH16543		
				V <sub>CC</sub> =		V <sub>CC</sub> =	2.7 V	V <sub>CC</sub> =		V <sub>CC</sub> =	2.7 V	UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>W</sub>	Pulse duration, L	uration, LEAB or LEBA low				3.3		3.3		3.3		ns
		A or B before	Data high	0.5		0.5		0.5		0.5		
١.	Catua tima	LEAB↑ or LEBA↑	Data low	0.8		1.3		0.8		1.3		ns
t <sub>su</sub>	Setup time	A or B before	Data high	0		0		0		0		115
		CEAB↑ or CEBA↑	Data low	0.6		1.1		0.6		1.1		
		A or B after	Data high	1.5	2	0.7		1.5		0.7		
١.	Hold time	<del>  </del>	Data low	1.2	20	1.3		1.2		1.3		no
t <sub>h</sub>	rioid tiffle	A or B after	Data high	1.7	Q	0.9		1.7		0.9		ns
	<del>                                    </del>		Data low	1.6		1.8		1.6		1.8		

## switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

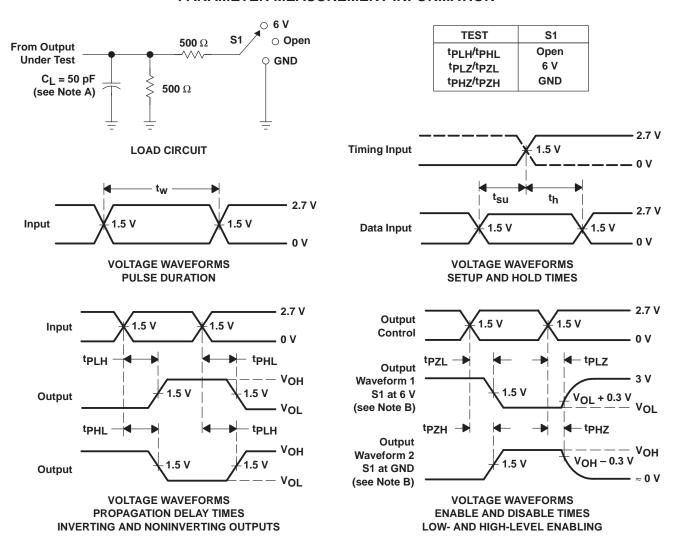
				SN54LV	ГН16543			SN74	LVTH16	6543		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> =		V <sub>CC</sub> =	2.7 V		CC = 3.3 ± 0.3 V	V	V <sub>CC</sub> =	2.7 V	UNIT
			MIN	MAX	MIN	MAX	MIN	TYP†	MAX	MIN	MAX	
t <sub>PLH</sub>	A or B	B or A	1.1	3.4		3.9	1.2	2.3	3.2		3.7	ns
t <sub>PHL</sub>	AOIB	BULK	1.1	3.4		3.9	1.2	2.1	3.2		3.7	115
t <sub>PLH</sub>	<u>LE</u>	A or B	1.2	4.1	1	5.1	1.3	2.5	3.9		4.9	ns
t <sub>PHL</sub>	LE	AUID	1.2	4.1	13/	5.1	1.3	2.3	3.9		4.9	115
<sup>t</sup> PZH	ŌĒ	A or B	1.2	4.5	13/	5.6	1.3	2.8	4.3		5.4	ns
t <sub>PZL</sub>	OE	A OF B	1.2	4.5	la	5.6	1.3	2.8	4.3		5.4	115
<sup>t</sup> PHZ	ŌĒ	A or B	1.9	4.9		5.4	2	3.5	4.7		5.2	ns
t <sub>PLZ</sub>	OE	AUB	1.9	4.6		4.7	2	3.3	4.4		4.5	115
<sup>t</sup> PZH	CE	A or B	1.2	4.7		5.8	1.3	3	4.5		5.6	no
t <sub>PZL</sub>	CE	AUID	1.2	4.7		5.8	1.3	3	4.5		5.6	ns
<sup>t</sup> PHZ	CE	A or B	1.9	5.1		5.6	2	3.6	4.9		5.4	ne
<sup>t</sup> PLZ	CE		1.9	4.9		5.1	2	3.5	4.7		4.9	ns

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .



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#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \ \Omega$ ,  $t_f \leq$  2.5 ns.  $t_f \leq$  2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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#### PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
SN74LVTH16543DGGR	ACTIVE	TSSOP	DGG	56	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH16543	Samples
SN74LVTH16543DL	ACTIVE	SSOP	DL	56	20	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH16543	Samples
SN74LVTH16543DLR	ACTIVE	SSOP	DL	56	1000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH16543	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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## **PACKAGE OPTION ADDENDUM**

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

#### OTHER QUALIFIED VERSIONS OF SN74LVTH16543:

• Enhanced Product : SN74LVTH16543-EP

NOTE: Qualified Version Definitions:

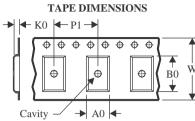
• Enhanced Product - Supports Defense, Aerospace and Medical Applications

## **PACKAGE MATERIALS INFORMATION**

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## TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVTH16543DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1
SN74LVTH16543DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1

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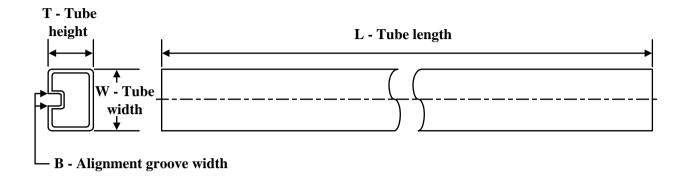
### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
SN74LVTH16543DGGR	TSSOP	DGG	56	2000	367.0	367.0	45.0	
SN74LVTH16543DLR	SSOP	DL	56	1000	367.0	367.0	55.0	

## **PACKAGE MATERIALS INFORMATION**

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## **TUBE**

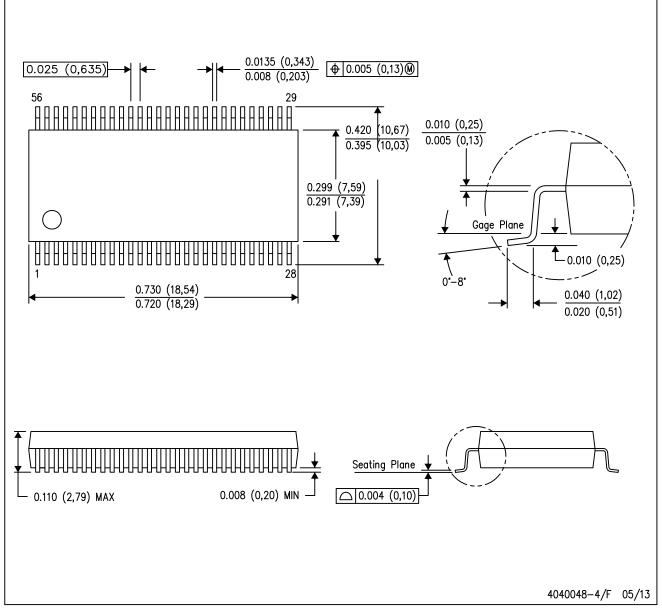


#### \*All dimensions are nominal

	Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
ı	SN74LVTH16543DL	DL	SSOP	56	20	473.7	14.24	5110	7.87

## DL (R-PDSO-G56)

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

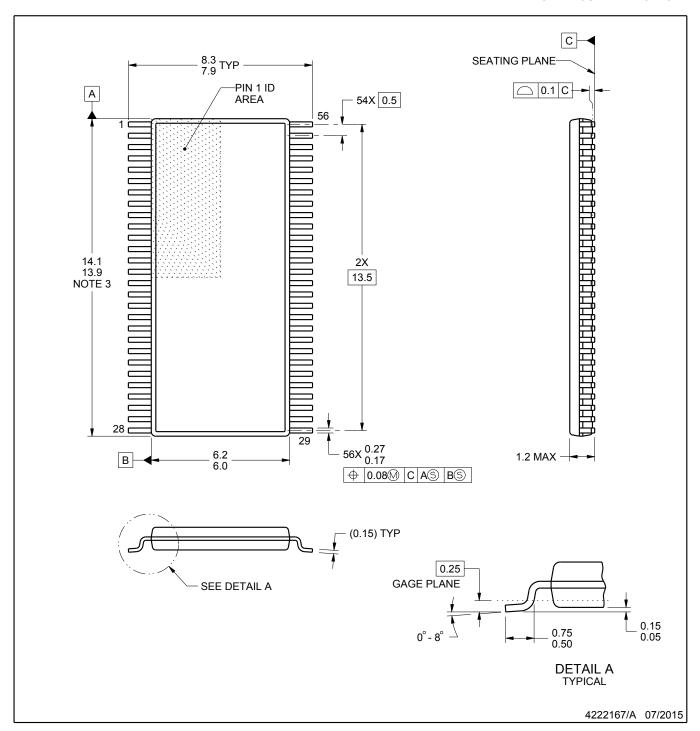
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

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SMALL OUTLINE PACKAGE



#### NOTES:

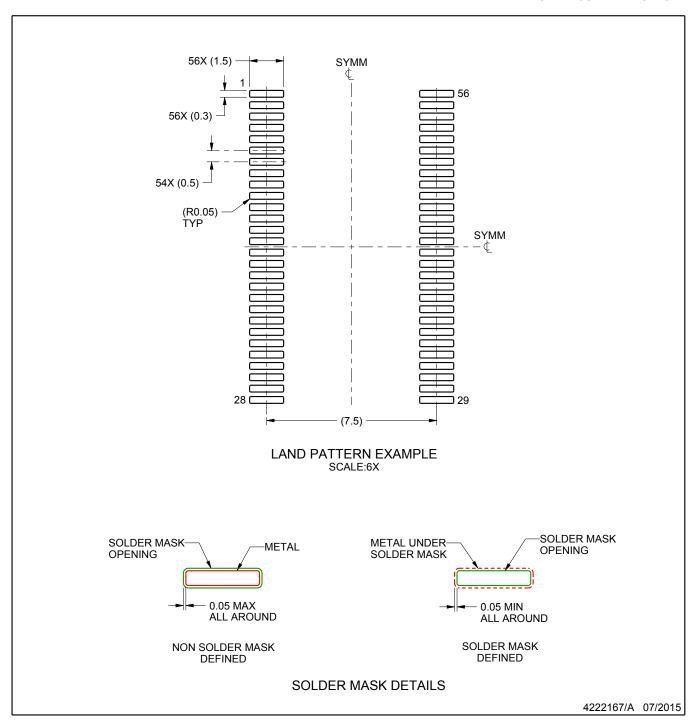
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
  4. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE

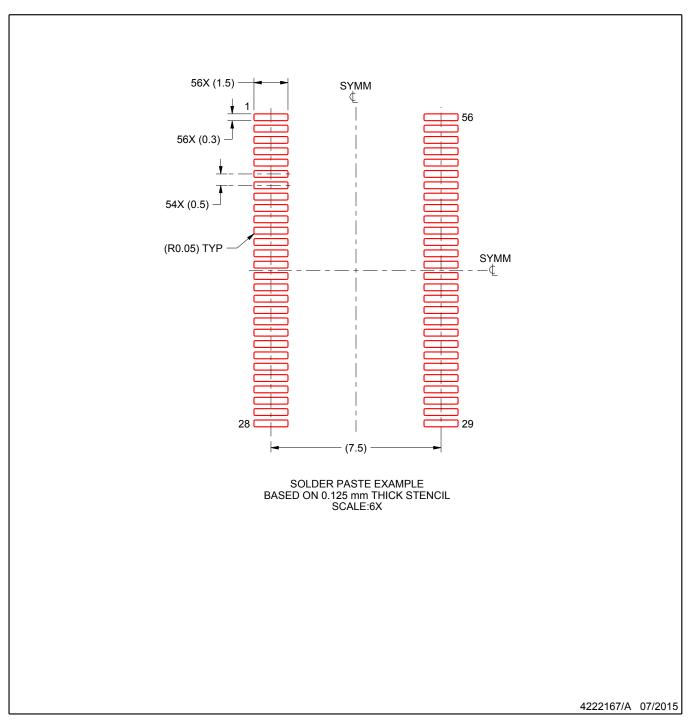


NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



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